

In the claims

Cancel claims 8-19 and 27-38.

Remaining claims are 1-7 and 20-26.

1 1. A process for fabricating a thin-film magnetic head having an air bearing
2 surface (ABS), the method comprising the unordered steps of:

- 3 (a) polishing the surface of a first side of a monolithic substrate wafer;
4 (b) forming on the surface of the first side of the monolithic substrate wafer
5 a first array of magnetic read head structures and magnetic write head structures each
6 having a head gap;
7 (c) polishing the surface of the other side of the monolithic substrate wafer;
8 (d) forming on the surface of the other side of the monolithic substrate wafer
9 a second array of magnetic read head structures and magnetic write head structures
10 disposed such that a plurality of the magnetic read head gaps on one of the monolithic
11 substrate surfaces are each aligned to form a read/write track-pair with a corresponding
12 one of the magnetic write head gaps on the other monolithic substrate surface;
13 (e) cutting the monolithic substrate to expose the head gaps of a plurality of
14 read/write track-pairs; and
15 (f) lapping the ABS to refine the depth of the exposed head gaps.

1 2. The method of claim 1 wherein the first and second arrays comprise:
2 a plurality of magnetic read and write head structures disposed such that each
3 read head structure is covered by a collocated write head structure in a piggy-back
4 configuration.

1 3. The method of claim 2 wherein each of the magnetic read heads includes
2 a magnetoresistive (MR) sensor element.

1 4. The method of claim 1 further comprising the step of:
2 (h) cutting the monolithic substrate to separate therefrom a thin-film magnetic
3 head having a single read/write track-pair.

1 5. The method of claim 4 wherein each of the magnetic read heads includes
2 a magnetoresistive (MR) sensor element.

1 6. The method of claim 1 wherein the first array comprises a plurality of
2 magnetic read head structures adjoining one another and the second array comprises a
3 plurality of magnetic write head structures adjoining one another.

1 7. The method of claim 1 wherein each of the magnetic read heads includes
2 a magnetoresistive (MR) sensor element.

- 8. (Canceled)
- 9. (Canceled)
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- 12. (Canceled)
- 13. (Canceled)
- 14. (Canceled)
- 15. (Canceled)
- 16. (Canceled)
- 17. (Canceled)
- 18. (Canceled)
- 19. (Canceled)

1 20. A process for fabricating a thin-film magnetic head having an air bearing
2 surface (ABS), the method comprising the unordered steps of:

- 3 (a) polishing the surface of a front side of a monolithic substrate wafer;
- 4 (b) forming on the surface of the front side of the monolithic substrate wafer
5 an array of magnetic read head structures and magnetic write head structures each having
6 a head gap;
- 7 (c) sectioning the monolithic substrate wafer to form a plurality of wafer
8 subsections each having a back surface;
- 9 (d) fixing the back surfaces of a pair of the wafer subsections to one another
10 disposed such that a plurality of the magnetic read head gaps on the front surface of one
11 of the wafer subsections are each aligned to form a read/write track-pair with a
12 corresponding one of the magnetic write head gaps on the front surface of the other wafer
13 subsection;
- 14 (e) cutting the fixed pair of wafer subsections to expose the head gaps of a
15 plurality of read/write track-pairs; and
- 16 (f) lapping the ABS to refine the depth of the exposed head gaps.

1 **21.** The method of claim 20 wherein the first and second arrays comprise:
2 a plurality of magnetic read and write head structures disposed such that each
3 read head structure is covered by a collocated write head structure in a piggy-back
4 configuration.

1 **22.** The method of claim 21 wherein each of the magnetic read heads includes
2 a magnetoresistive (MR) sensor element.

1 **23.** The method of claim 20 further comprising the step of:
2 (h) cutting the fixed pair of wafer subsections to separate therefrom a
3 thin-film magnetic head having a single read/write track-pair.

1 **24.** The method of claim 23 wherein each of the magnetic read heads includes
2 a magnetoresistive (MR) sensor element.

1 **25.** The method of claim 20 wherein the array comprises a plurality of
2 magnetic read head structures adjoining one another.

1 **26.** The method of claim 20 wherein each of the magnetic read heads includes
2 a magnetoresistive (MR) sensor element.

- 27.** (Canceled)
- 28.** (Canceled)
- 29.** (Canceled)
- 30.** (Canceled)
- 31.** (Canceled)
- 32.** (Canceled)
- 33.** (Canceled)
- 34.** (Canceled)
- 35.** (Canceled)
- 36.** (Canceled)
- 37.** (Canceled)
- 38.** (Canceled)

In the abstract

Page 20, lines 1 and 2 amend the title from ~~A MONOLITHIC MAGNETIC READ-WHILE-WRITE HEAD APPARATUS AND METHOD OF MANUFACTURE~~ to METHOD OF MAKING A MONOLITHIC MAGNETIC READ-WHILE-WRITE HEAD APPARATUS.